




— 華半導體股份有限公司
MOSDESIGN SEMICONDUCTOR CORP.

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SIREN	
M3720	

1 KEY 1 SOUND

1 键 1 音效 IC

FEATURES 功能叙述

- LED flash output.
- Envelope generator selectable.
- Speaker or directly buzzer application.

P/N	SOUND		Fosc (KHz)	Rosc	应用
M3720-1	AIRPLANE	飞机声	64	390K	A
M3720-2	ROCKET	火箭声	96	220K	A
M3720-3	SIREN II	警报声 II	64	220K	A
M3720-4	POLICE CAR	警车声	128	150K	A
M3720-5	FIRE BRIGADE	救火车声	128	150K	A
M3720-6	SIREN I	警报声 I	64	360K	A
M3720-7	DIAL TONE	电话声	64	390K	B
M3720-8	CHICKEN	小鸡叫	260	62K	B
M3720-9	AMBULANCE	救护车声	64	390K	A
M3720-10	DAN 1 TIME	当声 1 次	64	390K	C

APPLICATION 产品应用

- Siren system, Home/Car alarm etc..

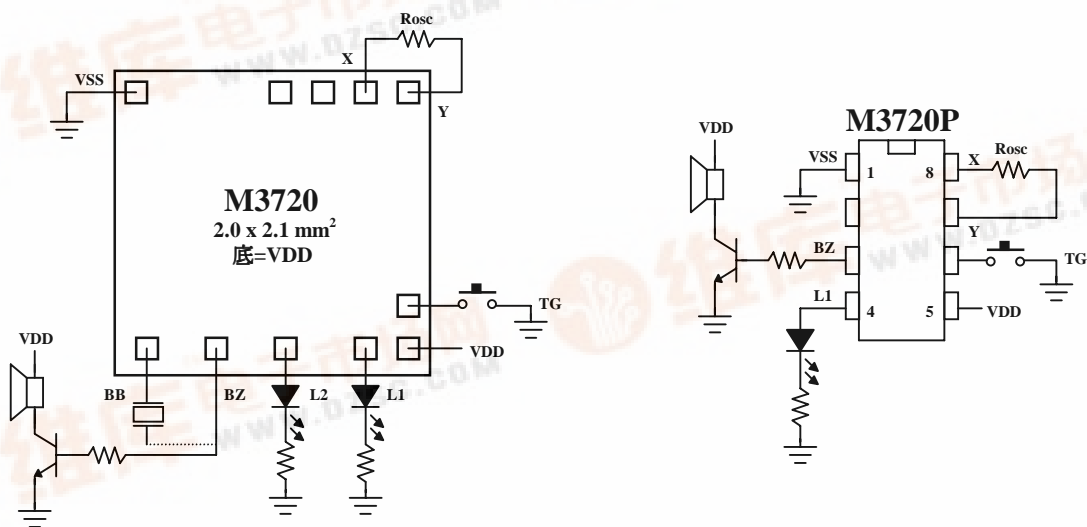
ELECTRICAL CHARACTERISTICS 电气规格

(@V_{DD}=3V unless otherwise specified)

Characteristics	Sym.	Min.	Typ.	Max.	Unit	REMARKS
工作电压 Operating Voltage	V _{DD}	—	3	3.5	V	
工作电流 Operating Current	I _{OP}	—	0.1	0.5	mA	No load
静态电流 Quiescent Current	I _{SB}	—	1	5	μ A	
推动电流 BZ Driving Current	I _O	1	—	—	mA	@ V _{DS} =1V
推动电流 LO Driving Current	I _{OL}	2	—	—	mA	@ V _{DS} =1.2V
振荡频率 Oscillator Frequency	F _{OSC}	—	—	—	KHz	External ± 30%
工作温度 Operating Temperature	Temp.	0	25	60	°C	

APPLICATION DIAGRAM 参考电路图


(A)





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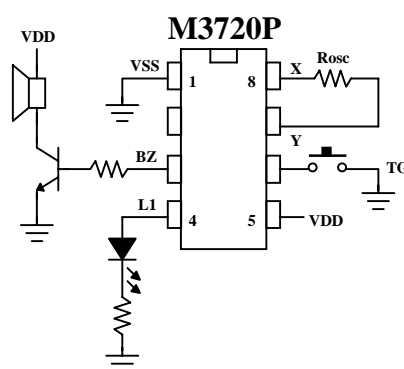
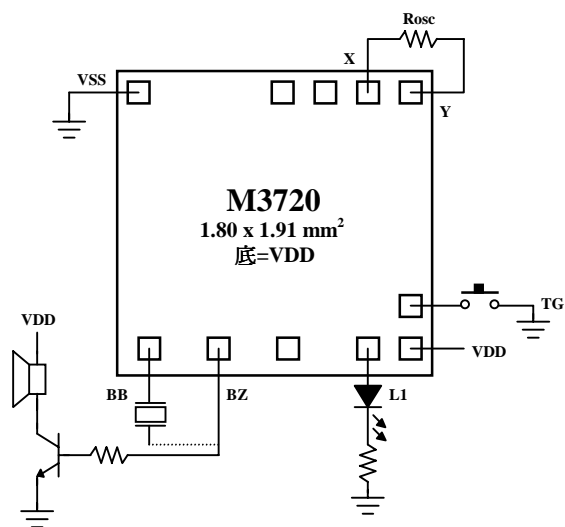
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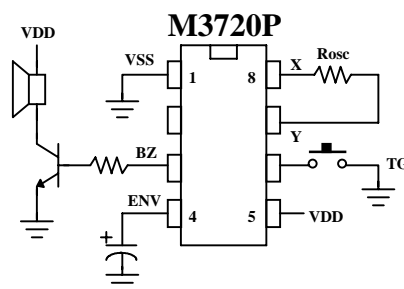
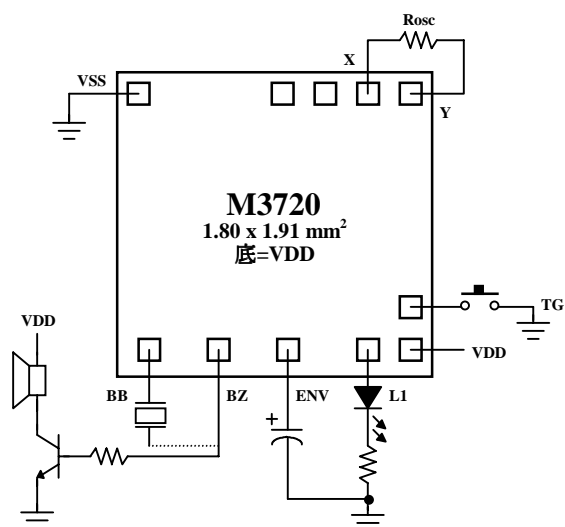
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APPLICATION DIAGRAM 参考电路图

(B)



(C)




*All specs and applications shown above subject to change without prior notice.

(以上电路及规格仅供参考,本公司得行修正)



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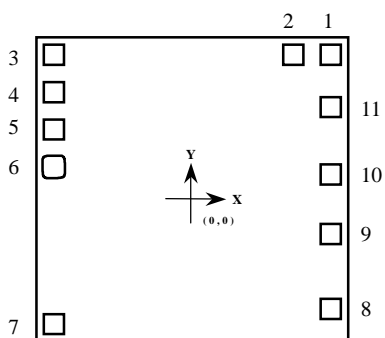
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PAD ASSIGNMENT & POSITION



UNIT : um

No.	NAME	X	Y
1	VDD	747	754
2	TG	537	754
3	Y	-749	754
4	X	-749	544
5	TEST	-749	334
6	T1	-749	124
7	VSS	-749	-754
8	BB	747	-653
9	BZ	747	-259
10	L2	747	80
11	L1	747	465

* CHIP SIZE ~ 1.80 x 1.91 mm²

* IC substrate should be connected to VDD in PCB (PCB 上 IC 必须接 VDD)